

#### ASIA PHOTONICS EXPO 26-28 February 2025

Sands Expo and Convention Centre, Singapore

# APPLICATION OF PHOTONICS TECHNOLOGY IN THE SEMICONDUCTOR INDUSTRY

Asia Photonics Expo (APE), a world's leading comprehensive photonics platform, will be held at the Sands Expo and Convention Centre in Singapore from 26 to 28 February 2025. It focuses on cutting-edge technologies and emerging markets in the fields of optical communication, optics, laser, infrared, sensing, and display, including optoelectronic chips, sensors, semiconductor materials, and semiconductor manufacturing/packaging and testing equipment. It serves as a one-stop platform for professionals in the semiconductor industry to seek upstream and downstream products, innovative technologies, engage in trade negotiations, and facilitate procurement.

#### **Exhibit Profile**

Optoelectronic Chips: VCSEL chips, sensor chips, high-speed modulator chips, pump laser chips, DFB and EML chips, etc.

**Sensors:** MEMS sensors, image sensors, vision sensors, infrared sensors, laser sensors, etc.

Semiconductor

**Semiconductor Materials:** Indium phosphide, gallium nitride, gallium arsenide, monocrystalline silicon, organic germanium, wafers, silicon substrates, target materials, mold materials, grinding materials, etc.

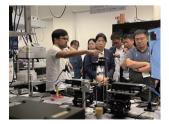
**Semiconductor Equipment:** Chip epitaxial equipment, chip dicing machines, pick-and-place machines, cleaning machines, scribing machines, semiconductor packaging and testing equipment, etc.

#### **CONCURRENT ACTIVITIES**



#### **Gala Dinner**

Over 120 top-level executives of our exhibitors and partners attended the gala dinner and took the opportunity to engage in high-level discussions, exchange ideas, and explore potential collaborations.



#### Site Tour

APE co-organized with Singapore University of Technology and Design and LUX Photonics Consortium to curate a site tour which attracted over 40 companies to join, aiming to link between academia and industry.



#### Happy Hours

It will be held at VIP lounge to facilitate the networking and collaboration between exhibitors and VIP visitors.

#### **CONCURRENT CONFERENCES**

#### **Application Forum**

A series of application programmes will be dedicated to showcasing the application fields within manufacturing, medical, consumer electronics, etc.

#### **Industry Forum**

Explore the cutting-edge optoelectronic technology and gain in-depth insights into its latest developments across various photonics application fields, thereby driving innovation in upstream and downstream products.





BOOTH APPLICATION

REGISTER AS A VISITOR



# Application of Photonics Technology in the Semiconductor Industry

Centre (Marina Bay Sands) Level Sands Expo and Convention 26-28 February 2025

\*Only part of exhibits, listed in no order

#### Silicon Wafer ---Semiconductor Material Material

 Infrared Temperature VCSEL/InGaAs Epitaxial Hybrid Bonding Wafer 8-inch Back-illuminated

Sensor Wafer

#### Crystal Thin Film Lithium Niobate Single Arsenide Epitaxial Layer Gallium Nitride/Gallium •Indium Phosphide /

## Ceramics

Diffuser

Shell

+HTCC (High-Temperature
Co-fired Ceramic)
-Laser Ceramic Reflector / CSOP Ceramic Packaging

 Diamond Grinding Fluid Nanoimprint Material Full Range of Imprint Photoresist Heat-Assisted UV

Polishing Pad Sapphire Polishing Pad

 Polyurethane Series Silicon Dioxide Polishing Polishing Slurry/ Pad

Discs

Grinding Pad
 Fiber Optic Grinding

SIC Polishing Slurry

Semiconductor Target
•UV Debonding Film Ceramic Substrate
Silicon Nitride Ceramic Aluminum Oxide Management Substrate Silicon Carbide Thermal

Sputtering TargetMetal Oxide

reflective Coating

Target / UV Anti-

## Solder Ball

Grinding Wheel •Gold Solder Ball Ceramic Diamond

# 

## Photoresist ---

Grinding Material

Photoresist Verification

## Grinding Wheel /

 Resin Grinding Wheel Thinning Grinding Wheel

## Transmitting Chip APD Chip Optical Chip Component

# Optoelectronics

# Optoelectronic Chip

•High-Speed Optical Detector Chip •800G DR8 •800G Silicon Optical Chip Detector Chip

Electronic Chip
LD Driver Chip
TIA Chip
DSP OLT Chip

Chip VCSEL / Lase •50G PAM4

Multi-junction
VCSEL Chip
•940nm TOF
VCSEL Chip VCSEL
Automotive
VCSEL Chip and

> ·SiPM LiDAR VLR Chip

Temperature Sensing Chip Processing ASIC Chip •50-Megapixel channel Signal High-Precision Multi-

# Optical Communication

 Optical Module Passive Optical Componen Active Optical Component

•OLED Ė MicroLED •MiniLED

# Optical Display Component

Photodetector

 PIN Photodiode Photomultiplier Tube Avalanche Photodiode

# **Manufacturing Equipment**

#### Etching Equipment ithography /

 Sapphire Polishing Pad Polishing Pad Polyurethane Series Polishing Slurry •SIC Polishing Slurry
•Silicon Dioxide

Wet Oxidation Furnace

De-gas Furnace

•PVD Coating Equipment
•Roll-to-Roll PVD Vacuum Coating Equipment CMP Polishing Machine Equipment

# **Electroplating Equipment**

PVD Equipment

Polishing Machines /

# CVD Equipment /

•CVD Equipment
•Plasma Enhanced CVD Wafer Electroplating

#### Vacuum Bridging Furnace Oxidation Furnace Annealing Furnace / Thin Film Deposition

 Vacuum Reflow Furnace •CVD Equipment
•Nano Film Layer
Deposition System
•Linear Multi-chamber Thin

Film Deposition System

# Cleaning Machine

 Single Wafer Cleaner
 Ultrasonic Cleaner •Plasma Cleaner Wafer Cleaning

# Lamination machine Coupling Machine

Automatic Optical Path Coupling Machine

Packaging & Testing Equipment

•Fully Automatic
Thinning Machine Wafer Thinning Machin

Machine Automatic Lamination

System Coupling Alignment Waveguide Combiner

## Mounting Machine /

Oven

 High-Precision Epoxy
 Mounter Micro-Precision Mounte UVLED Oven

Vacuum Pressure Oven

 Wafer Laser Sorter Chip Sorter

**Precision Sorter** Fully Automatic High-

# **Bonding Machine**

Machine Wire Bonding Machine
 Multi-Function Bonding Bonding Machine High-Precision Chip

# Die Bonder

 Semiconductor Dual-•COB Die Bonder High-Speed Die Bonder Head Die Bonder

# Cleaning / Welding / Cutting Equipment

Dicing Machine

Automatic Dicing Machine 8-inch Single-Axis Semi- Dual-Axis Precision Dicing LD/PD Chip Dicing Machin Equipment Marking Machine Fully Automatic PCB Laser Laser Cleaning Machine
 Solder Ball Welding Machine Semiconductor Cutting

> Temperature Sensor Detection Sensor Material Sensor

# Intelligent Sensor

#### Multi-line Mechanical LiDAR LiDAR 3D Vision

Flight) TOF Ranging Sensor Vision Sensor •3D TOF (Time-of-CMOS Image Sensor

Sensor

 Infrared Carbon Dioxide Gas Leakage Detection Industrial Sensor

Ultra-Wide Angle Blind
 Spot Laser Radar

Single-point Ranging

# Image Sensor and Module

MEMS Sensor

 Projector Module Other Sensors ·Capacitive Angle Sensor

 Fiber Optic Gyroscope Micro Electrostatic

# Measuring & Test Instrument

#### Instrument Testing / Measurement

 Temperature Cycling Test Chamber (Hot and Cold Shock Tester) Testing Equipment Semiconductor Laser COS

Interferometer

Interferometer
•Vertical Laser
Interferometer
•Non-contact Laser Multi-wavelength Laser

•3D Optical Profiler
•Line Laser Profiler
•Probe-Based Surface

Station
•Silicon Photonics Probe VCSEL Wafer Probe

Probe Testing Equipment

Measuring Instrument

# Measuring Instrument Spectrometer

•3D Topography Measuring InstrumentHigh-Precision Vision Measuring Instrument Wafer Warp and Stress Spectrometer

# Infrared Thermal Imaging

•Cooling Spectrometer
•Near-Infrared imaging core solution

# Microscope

 Infrared Thermal Imager ASIC-based thermal Infrared Detection Ultra-Deep Focus Video Stereo Microscope 3D Imaging Microscope

# Optical Inspection

Inspection Equipment
-Semiconductor Wafer AOI AOI Intelligent Appearance Mask AOI Equipment Equipment

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